

DATA SHEET

NETWORK CHIP RESISTORS

YC158 (10Pin/8R; Pb Free)

5%

sizes 0612; type T



SCOPE

This specification describes YC158 series chip resistor network with lead-free terminations made by thick film process.

ORDERING INFORMATION

Part number is identified by the series, size, tolerance, packing type, temperature coefficient, taping reel and resistance value.

YAGEO ORDERING CODE

CTC CODE

YC158T X X X XX XXXX L
(1) (2) (3) (4) (5) (6)

(1) TOLERANCE

J = $\pm 5\%$

(2) PACKAGING TYPE

R = Paper/PE taping reel

(3) TEMPERATURE COEFFICIENT OF RESISTANCE

– = Base on spec

(4) TAPING REEL

07 = 7 inch dia. Reel

13 = 13 inch dia. Reel

(5) RESISTANCE VALUE

56R, 560R, 5K6, 56K, 100K

(6) RESISTOR TERMINATIONS

L = Lead free terminations (pure Tin)

ORDERING EXAMPLE

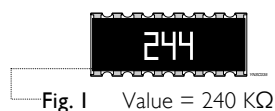
The ordering code of a YC158 convex chip resistor network, value 1,000 Ω with $\pm 5\%$ tolerance, supplied in 7-inch tape reel is: YC158TJR-071KL.

NOTE

1. The “L” at the end of the code is only for ordering. On the reel label, the standard CTC will be mentioned an additional stamp “LFP”= lead free production.
2. Products with lead in terminations fulfil the same requirements as mentioned in this datasheet.
3. Products with lead in terminations will be phased out in the coming months (before July 1st, 2006)

MARKING

YC158



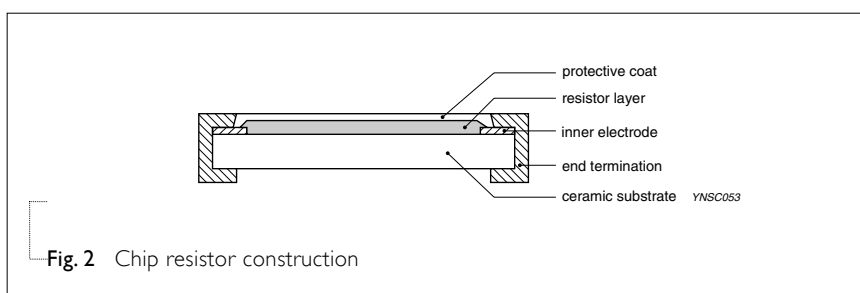
E-24 series: 3 digits

First two digits for significant figure and 3rd digit for number of zeros

For marking codes, please see EIA-marking code rules in data sheet “Chip resistors marking”.

CONSTRUCTION

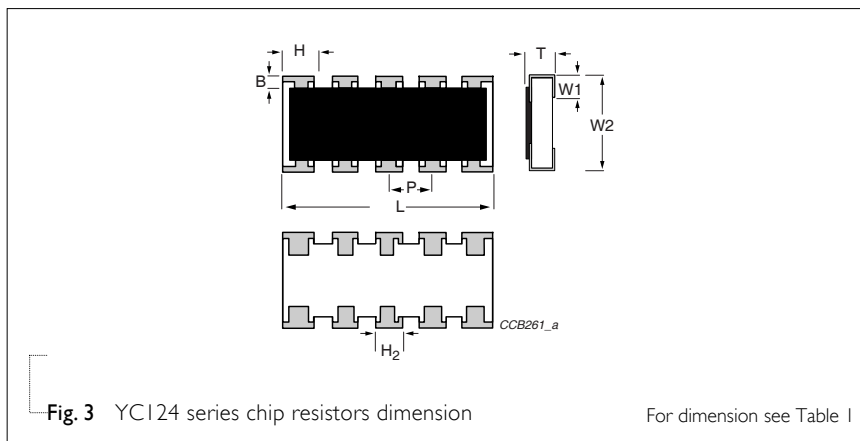
The resistors are constructed out of a high-grade ceramic body. Internal metal electrodes are added at each end and connected by a resistive paste. The composition of the paste is adjusted to give the approximate required resistance and laser cutting of this resistive layer that achieves tolerance trims the value. The resistive layer is covered with a protective coat. Finally, the ten external terminations (pure Tin) are added. See fig. 2.



DIMENSIONS

Table I

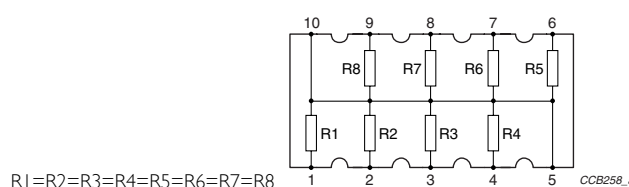
TYPE	YC158
B (mm)	0.30 ±0.15
H (mm)	0.45 ±0.05
P (mm)	0.64 ±0.05
L (mm)	3.20 ±0.20
H ₂ (mm)	0.35 ±0.05
T (mm)	0.60 ±0.10
W ₁ (mm)	0.35 ±0.15
W ₂ (mm)	1.60 ±0.15



SCHEMATIC

For dimension see Fig. 3 and Table I

Fig. 4 Equivalent circuit diagram



ELECTRICAL CHARACTERISTICS

Table 2

CHARACTERISTICS	YC158 1/32 W
Operating Temperature Range	-55 °C to +155 °C
Maximum Working Voltage	25 V
Maximum Overload Voltage	50 V
Dielectric Withstanding Voltage	50 V
Number of Resistors	8
Resistance Range	5% (E24) 10 Ω to 100 KΩ
Temperature Coefficient	±200 ppm/°C

FOOTPRINT AND SOLDERING PROFILES

For recommended footprint and soldering profiles, please see the special data sheet "Chip resistors mounting".

ENVIRONMENTAL DATA

For material declaration information (IMDS-data) of the products, please see the separated info "Environmental data" conformed to EU RoHS.

PACKING STYLE AND PACKAGING QUANTITY

Table 3 Packing style and packaging quantity

PRODUCT TYPE	PACKING STYLE	REEL DIMENSION	QUANTITY PER REEL
YC158	Paper / PE Taping Reel (R)	7" (178 mm)	5,000 units
		13" (330 mm)	20,000 units

NOTE

1. For Paper/PE tape and reel specification/dimensions, please see the special data sheet "Packing" document.

FUNCTIONAL DESCRIPTION**POWER RATING**

YC158 rated power at 70°C is 1/32 W

RATED VOLTAGE

The DC or AC (rms) continuous working voltage corresponding to the rated power is determined by the following formula:

$$V = \sqrt{(P \times R)}$$

Where

V = Continuous rated DC or AC (rms) working voltage (V)

P = Rated power (W)

R = Resistance value (Ω)

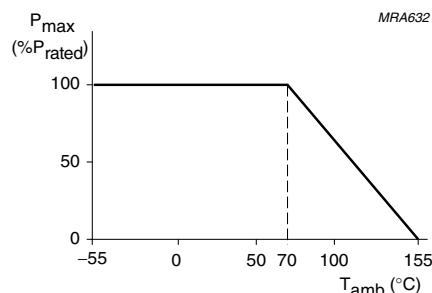


Fig. 5 Maximum dissipation (P_{max}) in percentage of rated power as a function of the operating ambient temperature (T_{amb})

TESTS AND REQUIREMENTS

Table 4 Test condition, procedure and requirements

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS				
Temperature Coefficient of Resistance (T.C.R.)	MIL-STD-202F-method 304; JIS C 5202-4.8	At +25/−55 °C and +25/+125 °C Formula: $T.C.R = \frac{R_2 - R_1}{R_1(t_2 - t_1)} \times 10^6 \text{ (ppm/°C)}$ Where t ₁ = +25 °C or specified room temperature t ₂ = −55 °C or +125 °C test temperature R ₁ = resistance at reference temperature in ohms R ₂ = resistance at test temperature in ohms	Refer to table 2				
Thermal Shock	MIL-STD-202F-method 107G; IEC 60115-1 4.19	At −65 (+0/−10) °C for 2 minutes and at +155 (+10/−0) °C for 2 minutes; 25 cycles	±(0.5% +0.05 Ω) for 1% tol. ±(1.0% +0.05 Ω) for 5% tol.				
Low Temperature Operation	MIL-R-55342D-Para 4.7.4	At −65 (+0/−5) °C for 1 hour; RCWV applied for 45 (+5/−0) minutes	±(0.5% +0.05 Ω) for 1% tol . ±(1.0% +0.05 Ω) for 5% tol. No visible damage				
Short Time Overload	MIL-R-55342D-Para 4.7.5; IEC 60115-1 4.13	2.5 × RCWV applied for 5 seconds at room temperature	±(1.0% +0.05 Ω) for 1% tol. ±(2.0% +0.05 Ω) for 5% tol. No visible damage				
Insulation Resistance	MIL-STD-202F-method 302; IEC 60115-1 4.6.1.1	RCOV for 1 minute <table><tr><td>Type</td><td>YC158</td></tr><tr><td>Voltage (DC)</td><td>50 V</td></tr></table>	Type	YC158	Voltage (DC)	50 V	≥10 GΩ
Type	YC158						
Voltage (DC)	50 V						
Dielectric Withstand Voltage	MIL-STD-202F-method 301; IEC 60115-1 4.6.1.1	Maximum voltage (V _{rms}) applied for 1 minute <table><tr><td>Type</td><td>YC158</td></tr><tr><td>Voltage (AC)</td><td>50 V_{rms}</td></tr></table>	Type	YC158	Voltage (AC)	50 V _{rms}	No breakdown or flashover
Type	YC158						
Voltage (AC)	50 V _{rms}						
Resistance to Soldering Heat	MIL-STD-202F-method 210C; IEC 60115-1 4.18	Unmounted chips; 260 ±5 °C for 10 ±1 seconds	±(0.5% +0.05 Ω) for 1% tol. ±(1.0% +0.05 Ω) for 5% tol. No visible damage				
Life	MIL-STD-202F-method 108A; IEC 60115-1 4.25.1	At 70 ±2 °C for 1,000 hours; RCWV applied for 1.5 hours on and 0.5 hour off	±(1% +0.05 Ω) for 1% tol. ±(3% +0.05 Ω) for 5% tol.				

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS	
Solderability	MIL-STD-202F-method 208A; IEC 60115-1 4.17	Solder bath at 245 ± 3 °C Dipping time: 2 ± 0.5 seconds	Well tinned ($\geq 95\%$ covered) No visible damage	
Bending Strength	JIS C 5202.6.14; IEC 60115-1 4.15	Resistors mounted on a 90 mm glass epoxy resin PCB (FR4) Bending: 1 mm	$\pm(1.0\% + 0.05 \Omega)$ for 1% tol. $\pm(1.0\% + 0.05 \Omega)$ for 5% tol. No visible damage	
Resistance to Solvent	MIL-STD-202F-method 215; IEC 60115-1 4.29	Isopropylalcohol (C_3H_7OH) or dichloromethane (CH_2Cl_2) followed by brushing	No smeared	
Noise	JIS C 5202 5.9; IEC 60115-1 4.12	Maximum voltage (V_{rms}) applied.	Resistors range	Value
			$R < 100 \Omega$	10 dB
			$100 \Omega \leq R < 1 K\Omega$	20 dB
			$1 K\Omega \leq R < 10 K\Omega$	30 dB
			$10 K\Omega \leq R < 100 K\Omega$	40 dB
			$100 K\Omega \leq R < 1 M\Omega$	46 dB
			$1 M\Omega \leq R \leq 22 M\Omega$	48 dB
Humidity (steady state)	JIS C 5202 7.5; IEC 60115-8 4.24.8	1,000 hours; 40 ± 2 °C; 93(+2/-3)% RH RCWV applied for 1.5 hours on and 0.5 hour off	$\pm(0.5\% + 0.05 \Omega)$ for 1% tol. $\pm(2.0\% + 0.05 \Omega)$ for 5% tol.	
Leaching	EIA/IS 4.13B; IEC 60115-8 4.18	Solder bath at 260 ± 5 °C Dipping time: 30 ± 1 seconds	No visible damage	
Intermittent Overload	JIS C 5202 5.8	At room temperature; $2.5 \times$ RCWV applied for 1 second on and 25 seconds off; total 10,000 cycles	$\pm(1.0\% + 0.05 \Omega)$ for 1% tol. $\pm(2.0\% + 0.05 \Omega)$ for 5% tol.	
Resistance to Vibration	On request	On request		
Moisture Resistance Heat	MIL-STD-202F-method 106F; IEC 60115-1 4.24.2	42 cycles; total 1,000 hours Shown as Fig. 6	$\pm(0.5\% + 0.05\Omega)$ for 1% tol. $\pm(2.0\% + 0.05\Omega)$ for 5% tol. No visible damage	

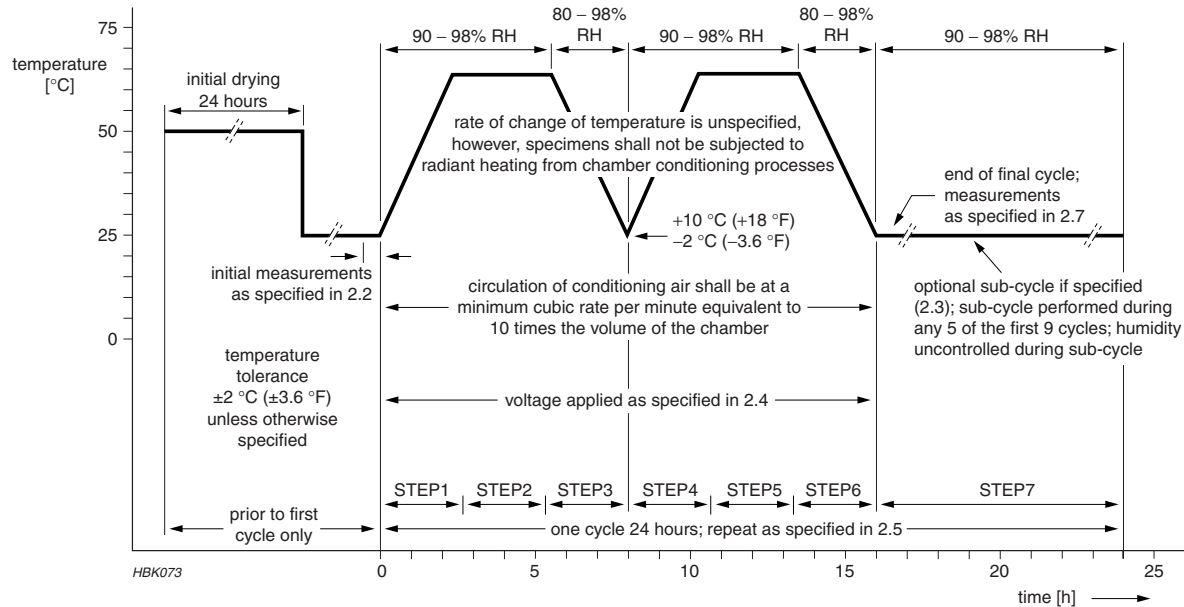


Fig. 6 Moisture resistance test requirements

REVISION HISTORY

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version 2	Feb 22, 2005	-	- Test method and procedure updated
Version 1	Apr. 22, 2004	-	- Added 13" taping and Jumper, deleted G in ordering code, and test & requirement (Pb free) update
Version 0	Nov. 10, 2003	-	- First issue of this specification